Product / Package Information

Package	SOIC_W_FP
Body Size	300 mils
Lead Count	28
Terminal Finish	100Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.35 E-01	93.70	937000	63.45	634537
Thermosets	Epoxy Resin	Proprietary	1.07 E-02	3.00	30000	2.03	20316
Thermosets	Phenol Resin	Proprietary	1.07 E-02	3.00	30000	2.03	20316
Other inorganic materials	Carbon Black	1333-86-4	1.07 E-03	0.30	3000	0.20	2032
Subtotal			3.57E-01	100.0	1000000	67.72	677201

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.44 E-01	97.5	975000	27.24	272375
Copper & its alloys	Iron	7439-89-6	3.46 E-03	2.35	23500	0.66	6565
Copper & its alloys	Zinc	7440-66-6	1.77 E-04	0.12	1200	0.03	335
Copper & its alloys	Phosphorus	7723-14-0	4.42 E-05	0.03	300	0.01	84
Subtotal			1.47 E-01	100	1000000	27.94	279359

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.35 E-03	100	1000000	1.01	10132

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.89 E-03	100	1000000	0.55	5476

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.28 E-04	100.00	1000000	0.18	1759

Chip/s

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.25 E-02	100	1000000	2.37	23686

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon dioxide	60676-86-0	6.09 E-04	48.30	483000	0.1153	1153
Other organic materials	Bismaleimide monomer	TS #10049	3.94 E-04	31.25	312500	0.0746	746
Other organic materials	Acrylate monomer	TS #10050	1.07 E-04	8.52	85200	0.0203	203
Thermoset	Epoxy resin	TS #10042	1.07 E-04	8.5	85200	0.0203	203
Other organic materials	Acryric resin	TS #10051	4.30 E-05	3.4	34100	0.0081	81
Subtotal			1.26 E-03	100.00	1000000	0.24	2388

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.28 E-01**	100	1000000

Control ID: MS012729 PKG5930

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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